

JEDEC STANDARD

Definition of the SSTUB32869 Registered Buffer with Parity for DDR2 RDIMM Applications

JESD82-27.01

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Definition of the SSTUB32869 Registered Buffer with Parity for DDR2 RDIMM Applications

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DEFINITION OF THE SSTUB32869 REGISTERED BUFFER WITH PARITY FOR DDR2 RDIMM APPLICATIONS

From JEDEC Board Ballot JCB-07-43, formulated under the cognizance of the JC-40 Committee on Digital Logic.

1 Scope

This standard defines standard specifications of DC interface parameters, switching parameters, and test loading for definition of the SSTUB32869 registered buffer with parity for driving heavy load on high-density DDR2 RDIMM applications. A typical application would be a 36 SDRAM planar DIMM.

The SSTUB32869 is identical in functionality to the SSTU32S869, SSTU32D869 SSTUA32S869, and SSTUA32D869 devices respectively but specify tighter timing characteristics and a higher application frequency of up to 410 MHz.

The purpose is to provide a standard for the SSTUB32869 (see Note) logic devices, for uniformity, multiplicity of sources, elimination of confusion, ease of device specification, and ease of use.

NOTE The designation SSTUB32869 refers to the part designation of a series of commercial logic parts common in the industry. This number is normally preceded by a series of manufacturer specific characters to make up a complete part designation.

2 Device Standard

2.1 Description

This 14-bit 1:2 registered buffer with parity is designed for 1.7 V to 1.9 V V_{DD} operation.

All clock and data inputs are compatible with the JEDEC standard for SSTL_18. The control inputs are LVCMOS. All outputs are 1.8 V CMOS drivers optimized to drive the DDR2 DIMM load, following the SSTL_18 standard. They provide 50% more dynamic driver strength than the standard SSTUB32866 outputs.

The SSTUB32869 operate from a differential clock (CK and \overline{CK}). Data are registered at the crossing of CK going high, and \overline{CK} going low.

The device supports low-power standby operation. When the reset input (\overline{RESET}) is low, the differential input receivers are disabled, and un-driven (floating) data, clock and reference voltage (V_{REF}) inputs are allowed. In addition, when \overline{RESET} is low all registers are reset, and all outputs except \overline{PTYERR} are forced low. The LVCMOS \overline{RESET} input must always be held at a valid logic high or low level.

To ensure defined outputs from the register before a stable clock has been supplied, \overline{RESET} must be held in the low state during power up.

In the DDR2 RDIMM application, \overline{RESET} is specified to be completely asynchronous with respect to CK and \overline{CK} . Therefore, no timing relationship can be guaranteed between the two. When entering reset, the register will be cleared and the outputs will be driven low quickly, relative to the time to disable the differential input receivers. However, when coming out of reset, the register will become active quickly, relative to the time to enable the differential input receivers.

2.1 Description (cont'd)

SSTUB32869 must ensure that the outputs remain low as long as the data inputs are low, the clock is stable during the time from the low-to-high transition of $\overline{\text{RESET}}$ and the input receivers are fully enabled. This will ensure that there are no glitches on the output. If the data inputs are not held low, then $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ must be held high, DODT and DCKE must be held low, and all other inputs must remain stable (either low or high) for a minimum of t_{ACT} (max) after the rising edge of $\overline{\text{RESET}}$.

The device monitors both $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ inputs and will gate the Q_n , PPO (Partial-Parity-Out) and $\overline{\text{PTYERRI}}$ (Parity Error) Parity outputs from changing states when both $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ are high. If either $\overline{\text{DCS}}$ or $\overline{\text{CSR}}$ input is low, the Q_n , PPO and $\overline{\text{PTYERRI}}$ outputs will function normally. The $\overline{\text{RESET}}$ input has priority over the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ controls and will force the Q_n and PPO outputs low and the $\overline{\text{PTYERRI}}$ high.

The SSTUB32869 includes a parity checking function. The SSTUB32869 accept a parity bit from the memory controller at its input pin PARIN one or two cycles after the corresponding data input, compares it with the data received on the D-inputs and indicates on its open-drain $\overline{\text{PTYERRI}}$ pin (active low) whether a parity error has occurred. The number of cycles depends on the setting of C1, see Figure 6 and 7.

When used as a single device, the C1 inputs are tied low. When used in pairs, the C1 inputs are tied low for the first register (front) and the C1 inputs are tied high for the second register. When used as a single register, the PPO and $\overline{\text{PTYERRI}}$ signals are produced two clock cycles after the corresponding data input. When used in pairs, the $\overline{\text{PTYERRI}}$ signals of the first register are left floating. The PPO outputs of the first register are cascaded to the PARIN signals on the second register (back). The PPO and $\overline{\text{PTYERRI}}$ signals of the second register are produced three clock cycles after the corresponding data input. Parity implementation and device wiring for single and dual die is described in Figure 1.

If an error occurs, and the $\overline{\text{PTYERRI}}$ is driven low, it stays low for two clock cycles or until $\overline{\text{RESET}}$ is driven low. For the case where a parity error occurs just before the device enters the low-power mode (LPM), see Table 4 on page 8, Figure 18, Figure 8 on page 13, and Figure 20. The parity error output $\overline{\text{PTYERRI}}$ will be reset to high by $\overline{\text{RESET}}$ transitioning low and will not be decoded until after $\overline{\text{RESET}}$ goes high and $\overline{\text{DCS}}$ and/or $\overline{\text{CSR}}$ are asserted low.

The DIMM-dependent signals (DCKE, $\overline{\text{DCS}}$, $\overline{\text{CSR}}$ and DODT) are not included in the parity check computations.

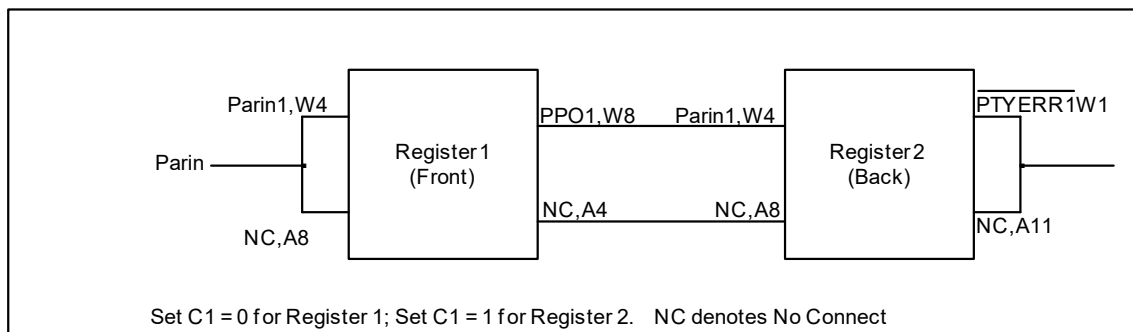


Figure 1 — Parity Implementation and Device Wiring for SSTUB32869

2.1 Description (cont'd)

Package options include 150-ball Thin Profile Fine Pitch BGA (TFBGA) (11×19 array, 8.0×13.0 mm body size, 0.65 mm pitch, 1.2 mm height, MO-246, Variation TBD).

2.2 150-ball TFBGA (MO-246xx)

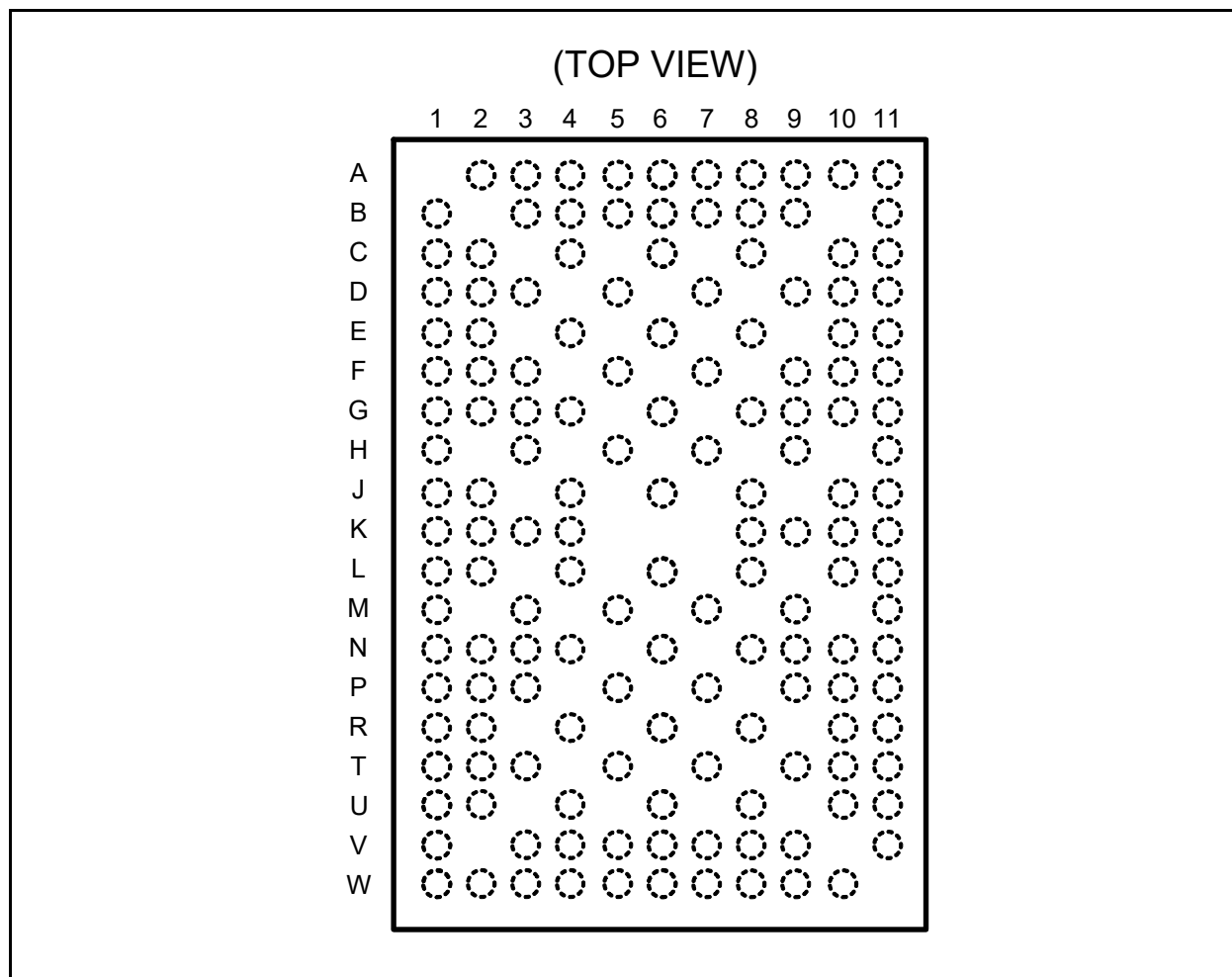


Figure 2 — Pinout Configuration

2.3 Pinout Top View for 150-ball TFBGA

150-ball, 11 × 19 grid, TOP VIEW

Figure 3 specifies the pinout for SSTUB32869. Unlike other configurable registers the device has symmetric pinout with center inputs and outputs to the left and right sides. Therefore the pinout for the device in front configuration is identical to pinout in back configuration. The recommended placement is back to back on both sides of the PCB. VIAs for the inner ball connections (Vdd, GND, Inputs) are to be placed at the NB locations.

	1	2	3	4	5	6	7	8	9	10	11
A	NB	VDD	MCL ⁽¹⁾	NC	GND	VREF	GND	NC	MCL ⁽¹⁾	VDD	NC
B	VDD	NB	VDD	GND	GND	GND	GND	GND	VDD	NB	VDD
C	QCKEA	VDD	NB	GND	NB	GND	NB	GND	NB	VDD	QCKEB
D	Q2A	VDD	GND	NB	DCKE	NB	D2	NB	GND	VDD	Q2B
E	Q3A	VDD	NB	D3	NB	NC	NB	DODT	NB	NC	Q3B
F	QODTA	VDD	GND	NB	NC	NB	NC	NB	GND	VDD	QODTB
G	Q5A	VDD	GND	D5	NB	CLK	NB	D6	GND	VDD	Q5B
H	Q6A	NB	GND	NB	NC	NB	NC	NB	GND	NB	Q6B
J	\overline{QCSA}	VDD	NB	NC	NB	\overline{RESET}	NB	\overline{CSR}	NB	VDD	\overline{QCSB}
K	VDD	VDD	GND	GND	NB	NB	NB	GND	VDD	VDD	VDD
L	Q8A	VDD	NB	\overline{DCS}	NB	\overline{CLK}	NB	D8	NB	VDD	Q8B
M	Q9A	NB	GND	NB	NC	NB	NC	NB	GND	NB	Q9B
N	Q10A	VDD	GND	D9	NB	NC	NB	D10	GND	VDD	Q10B
P	Q11A	VDD	GND	NB	NC	NB	NC	NB	GND	VDD	Q11B
R	Q12A	C1	NB	D11	NB	NC	NB	D12	NB	VDD	Q12B
T	Q13A	VDD	GND	NB	D13	NB	D14	NB	GND	VDD	Q13B
U	Q14A	VDD	NB	GND	NB	GND	NB	GND	NB	VDD	Q14B
V	VDD	NB	VDD	GND	GND	GND	GND	GND	VDD	NB	VDD
W	$\overline{PTYERRI}$	VDD	MCL ⁽¹⁾	PARIN1	GND	VREF	GND	PPO1	MCL ⁽¹⁾	VDD	NB

NB indicates no ball is populated at that gridpoint. NC denotes a no-connect (ball present but not connected to the die).

Note 1 MCL denotes input pins that must be connected Low. Register Vendors: Implement NC or input on Ball A3, A9, W3, and W9.

Figure 3 — Pinout Top View for 150-ball TFBGA

2.4 Terminal Functions

Table 1 — Terminal Functions

Signal Group	Signal Name	Type	Description
Ungated inputs	DCKE, DODT	SSTL_18	DRAM function pins not associated with Chip Select.
Chip Select gated inputs	D1 ... D14 ¹	SSTL_18	DRAM inputs, re-driven only when Chip Select is LOW.
Chip Select inputs	\overline{DCS} , \overline{CSR}	SSTL_18	DRAM Chip Select signals. These pins initiate DRAM address/command decodes, and as such at least one will be low when a valid address/command is present.
Re-driven outputs	Q1A...Q14A, Q1B ... Q14B, \overline{QCSA} , \overline{QCSB} QCKEA, QCKEB QODTA, QODTB	1.8 V CMOS	Outputs of the register, valid after the specified clock count and immediately following a rising edge of the clock.
Parity input	PARIN1	SSTL_18	Input parity is received on pin PARIN1 and should maintain parity across the D1...D14 ⁽¹⁾ inputs, at the rising edge of the clock, one clock cycle after Chip Select is LOW.
Parity output	PPO1	SSTL_18	Partial Parity Output. Indicates parity out of D1-D14 ⁽¹⁾
Parity error output	$\overline{PTYERR1}$	Open drain	When LOW, this output indicates that a parity error was identified associated with the address and/or command inputs. \overline{PTYERR} will be active for two clock cycles, and delayed by in total 2 clock cycles for compatibility with final parity out timing on the industry-standard DDR2 register with parity (in JEDEC definition).
Configuration Input	C1	1.8 V LVCMOS	When Low, register is configured as Register 1. When High, register is configured as Register 2.
Clock inputs	CK, \overline{CK}	SSTL_18	Differential main clock input pair to the register. The register operation is triggered by a rising edge on the positive clock input (CK).
Miscellaneous inputs	\overline{RESET}	1.8 V LVCMOS	Asynchronous reset input. When LOW, it causes a reset of the internal latches, thereby forcing the outputs LOW. \overline{RESET} also resets the $\overline{PTYERR1}$ signal.
	VREF	0.9 V nominal	Input reference voltage for the SSTL_18 inputs. Two pins (internally tied together) are used for increased reliability.
	VDD	Power Input	Power supply voltage
	GND	Ground Input	Ground
NOTE 1 Inputs D1, D4, D7, and their corresponding outputs Qn are not included in this range.			

2.5 Function Table

Table 2 — Function Table (each Flip Flop)

Inputs						Outputs		
$\overline{\text{RESET}}$	$\overline{\text{DCS}}$	$\overline{\text{CSR}}$	CK	$\overline{\text{CK}}$	Dn, DODT, DCKE	Qn	$\overline{\text{QCS}}$	QODT, QCKE
H	L	L	↑	↓	L	L	L	L
H	L	L	↑	↓	H	H	L	H
H	L	L	L or H	L or H	X	Q ₀	Q ₀	Q ₀
H	L	H	↑	↓	L	L	L	L
H	L	H	↑	↓	H	H	L	H
H	L	H	L or H	L or H	X	Q ₀	Q ₀	Q ₀
H	H	L	↑	↓	L	L	H	L
H	H	L	↑	↓	H	H	H	H
H	H	L	L or H	L or H	X	Q ₀	Q ₀	Q ₀
H	H	H	↑	↓	L	Q ₀	H	L
H	H	H	↑	↓	H	Q ₀	H	H
H	H	H	L or H	L or H	X	Q ₀	Q ₀	Q ₀
L	X or floating	X or floating	X or floating	X or floating	X or floating	L	L	L

Inputs							Output	
$\overline{\text{RESET}}$	$\overline{\text{DCS}}$	$\overline{\text{CSR}}$	CK	$\overline{\text{CK}}$	Σ of inputs = H D1...D14 ¹	PARIN1 ²	PPO1 ²	$\overline{\text{PTYERR1}}^3$
H	L	X	↑	↓	Even	L	L	H
H	L	X	↑	↓	Odd	L	H	L
H	L	X	↑	↓	Even	H	H	L
H	L	X	↑	↓	Odd	H	L	H
H	L	L	↑	↓	Even	L	L	H
H	L	L	↑	↓	Odd	L	H	L
H	L	L	↑	↓	Even	H	H	L
H	L	L	↑	↓	Odd	H	L	H
H	H	H	↑	↓	X	X	PPO _{n0}	$\overline{\text{PTYERR}}_{n0}$
H	X	X	L or H	L or H	X	X	PPO _{n0}	$\overline{\text{PTYERR}}_{n0}$
L	X or floating	X or floating	X or floating	X or floating	X or floating	X or floating	L	H

NOTE 1 Inputs D1, D4 and D7 are not included in this range.

NOTE 2 PARIN1 arrives one (C1=0) or two (C1=1) clock cycles after data to which it applies.

NOTE 3 This transition assumes $\overline{\text{PTYERR}}$ is high at the crossing of CK going high and $\overline{\text{CK}}$ going low. If $\overline{\text{PTYERR}}$ is low, it stays latched low for two clock cycles or until $\overline{\text{RESET}}$ is driven low. PARIN1 is used to generate PPO1 and $\overline{\text{PTYERR1}}$.

2.5 Function Table (cont'd)

Table 4 — Parity Error Detect in Low-power Mode¹

Input-Data Error Occurrence ²	1:2 Register-A Mode (C1=0)		1:2 Register-B Mode (C1=1)	
	PPO1 Duration ³	$\overline{\text{PTYERRI}}$ Duration ^{3,4}	PPO1 Duration ^{3,4}	$\overline{\text{PTYERRI}}$ Duration ³
n-2	1 Cycle	2 Cycles	1 Cycle	2 Cycles
n-1	1 Cycles after LPM is de-asserted	1 Cycles after LPM is de-asserted	2 Cycles after LPM is de-asserted	2 Cycles after LPM is de-asserted
n	Not detected	Not detected	Not detected	Not detected
NOTE 1 If a parity error occurs before the device enters the low-power mode (LPM), the behavior of PPO1 and $\overline{\text{PTYERRI}}$ is dependent on the mode of the device and the position of the parity error occurrence. This table illustrates the low-power-mode effect on <u>parity detect</u> . The low-power mode is activated on the n clock cycle when $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ go high.				
NOTE 2 The clock-edge position of a one-cycle data-input error relative to the clock-edge (n) which initiates LPM at the $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ inputs.				
NOTE 3 If an error occurs, the PPO output may be driven high and the $\overline{\text{PTYERRI}}$ output driven low. These columns show the clock duration for which the PPO signal will be held high or the $\overline{\text{PTYERRI}}$ signal will be held low.				
NOTE 4 Not used				

2.6 Logic Diagram

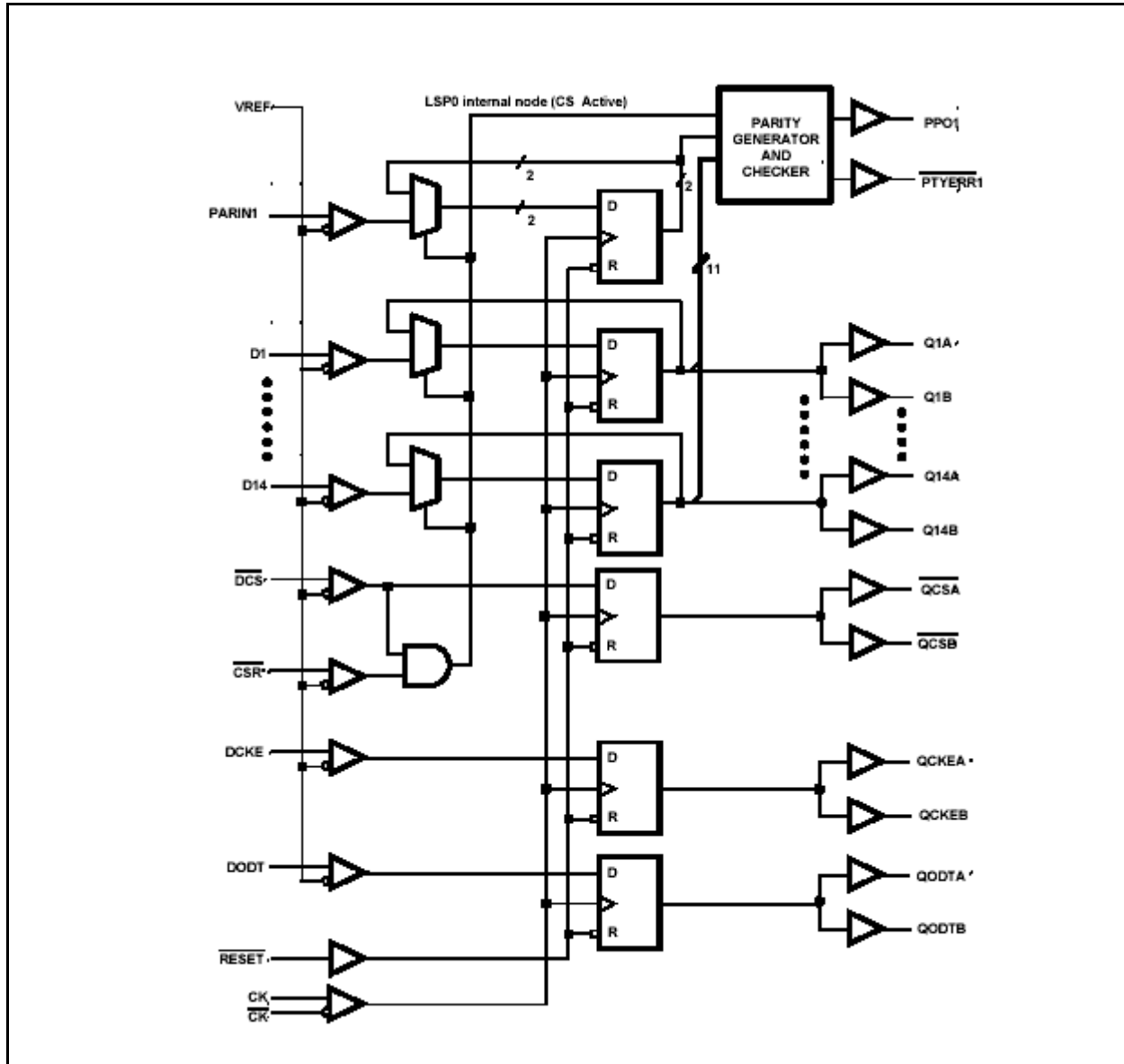


Figure 4 — Logic Diagram (Positive Logic)

2.7 Register Timing

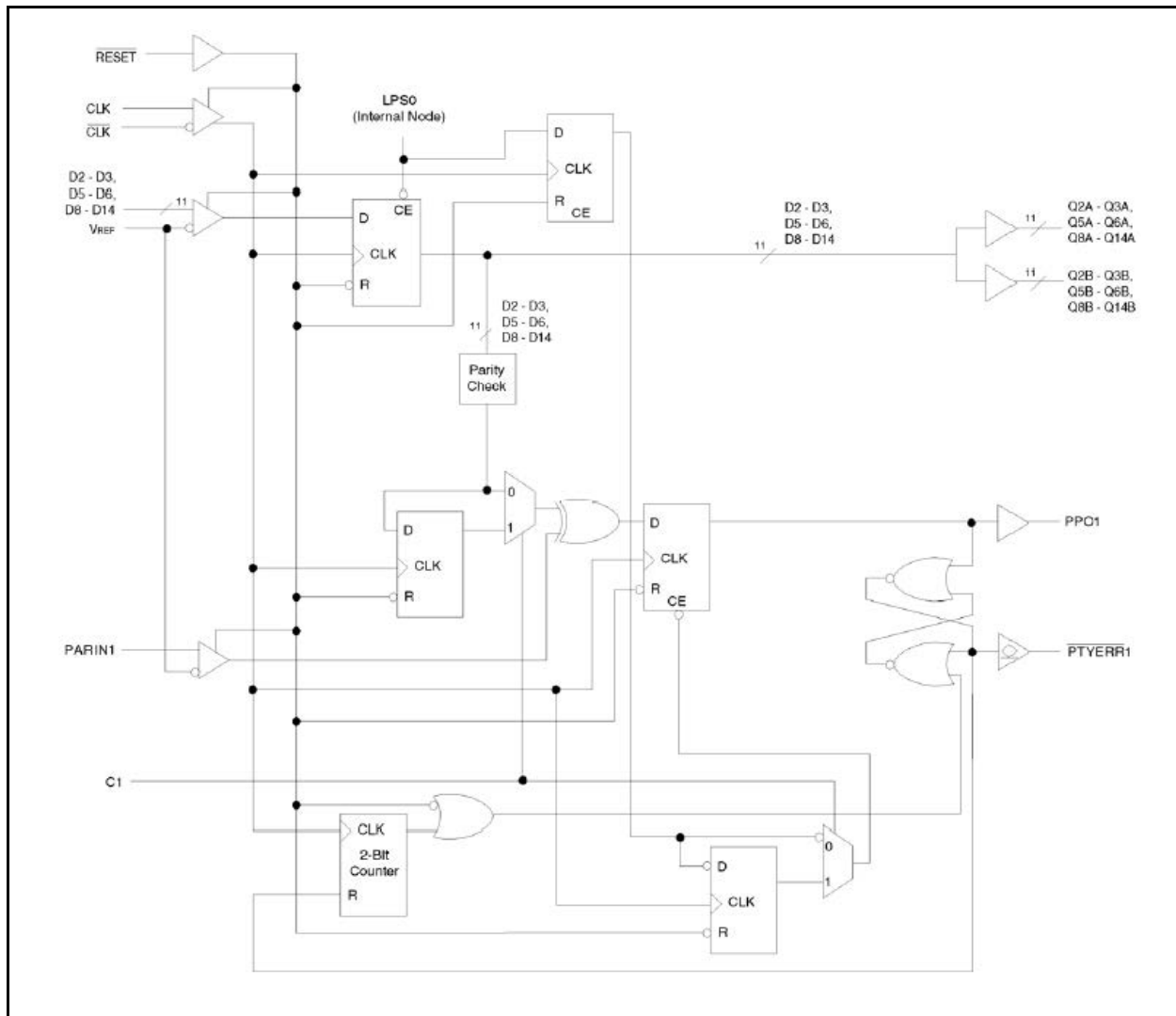
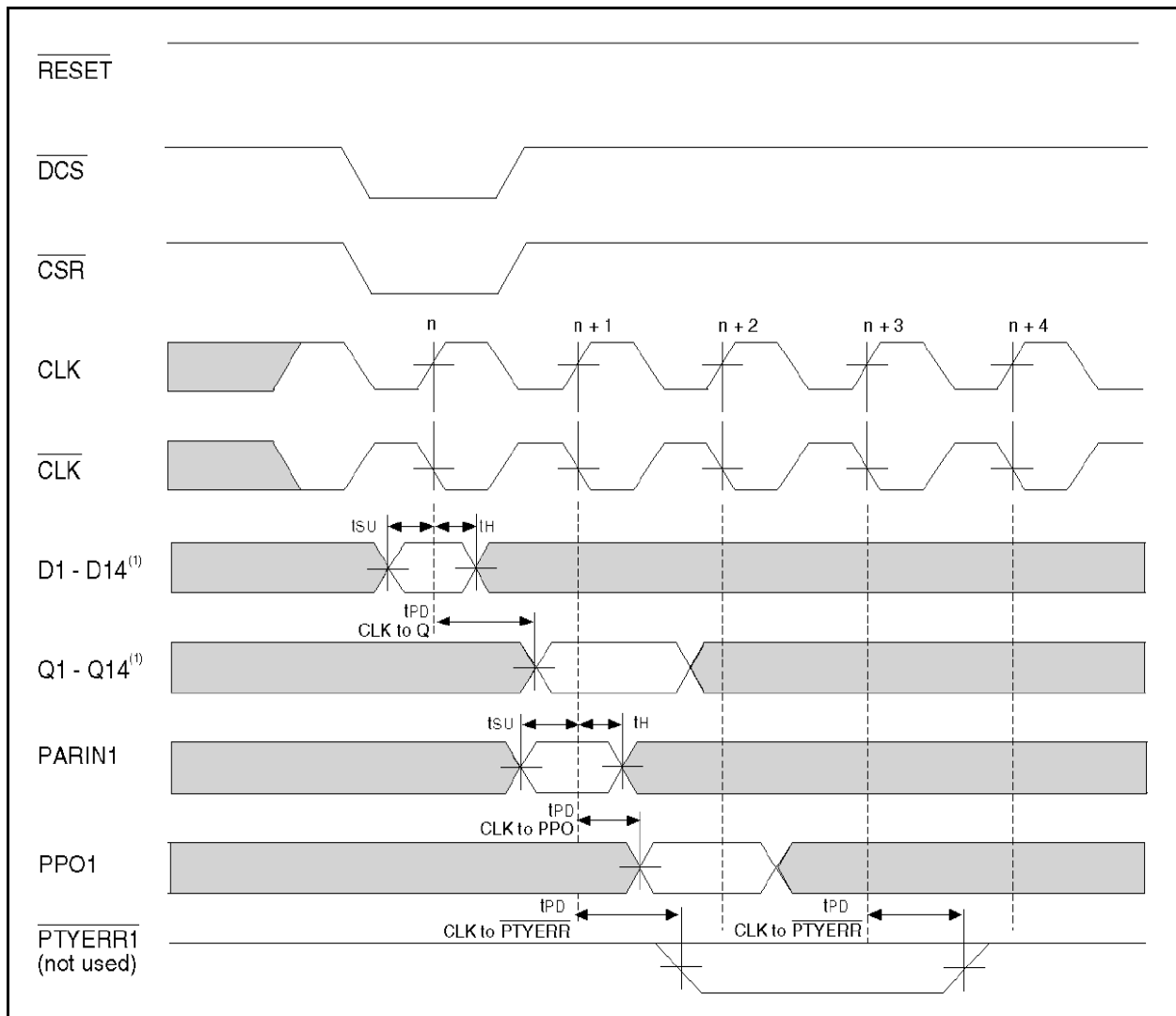


Figure 5 — Timing of Clock, Data, and Parity Signals

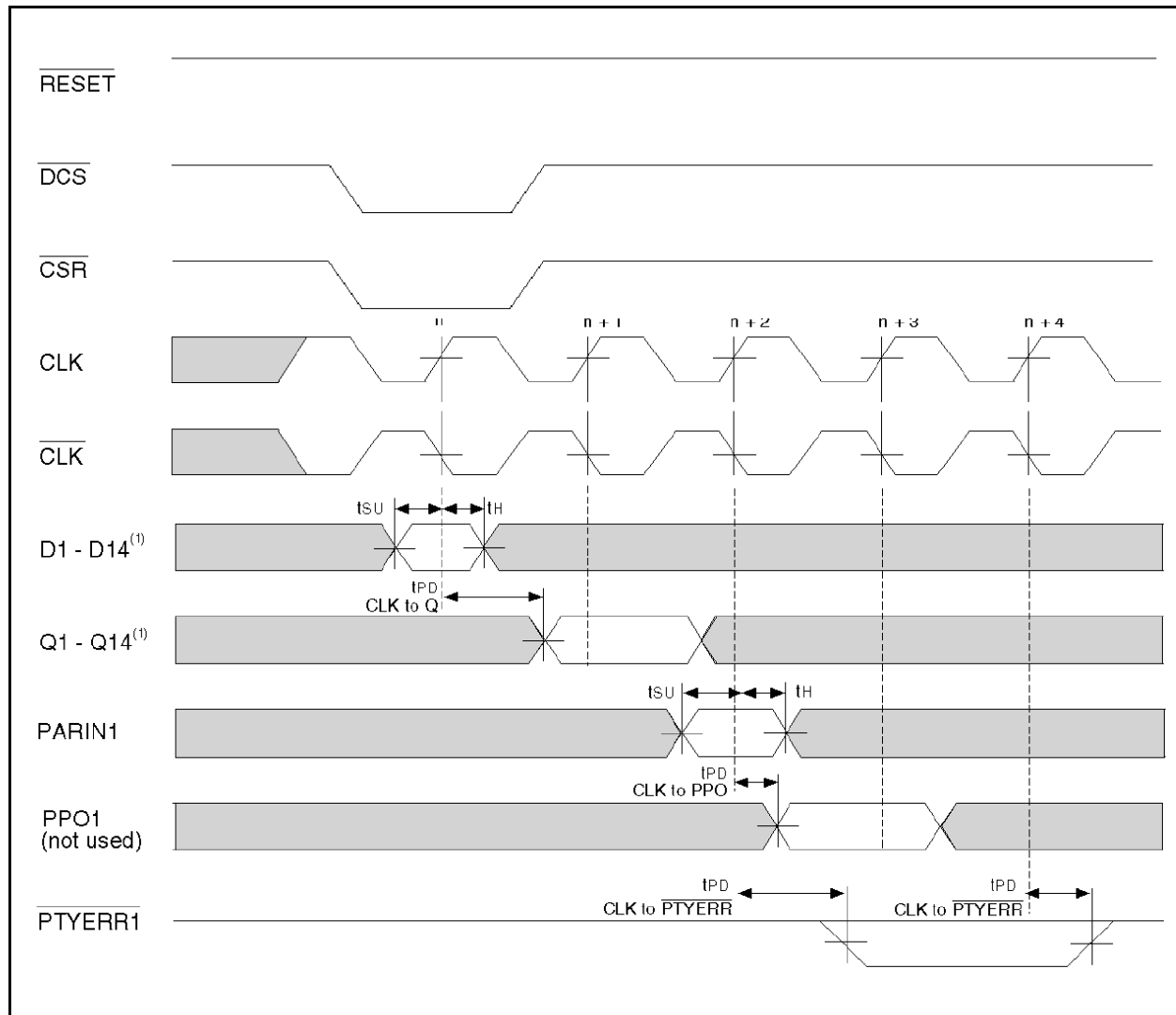
2.7 Register Timing (cont'd)



NOTE 1 This range does not include D1, D4, D7, and their corresponding outputs

Figure 6 — Timing Diagram for the 1st SSTUB32869 C1=0

2.7 Register Timing (cont'd)



NOTE 1 This range does not include D1, D4, D7, and their corresponding outputs

Figure 7 — Timing Diagram for the 2nd SSTUB32869, C1=1

2.7 Register Timing (cont'd)

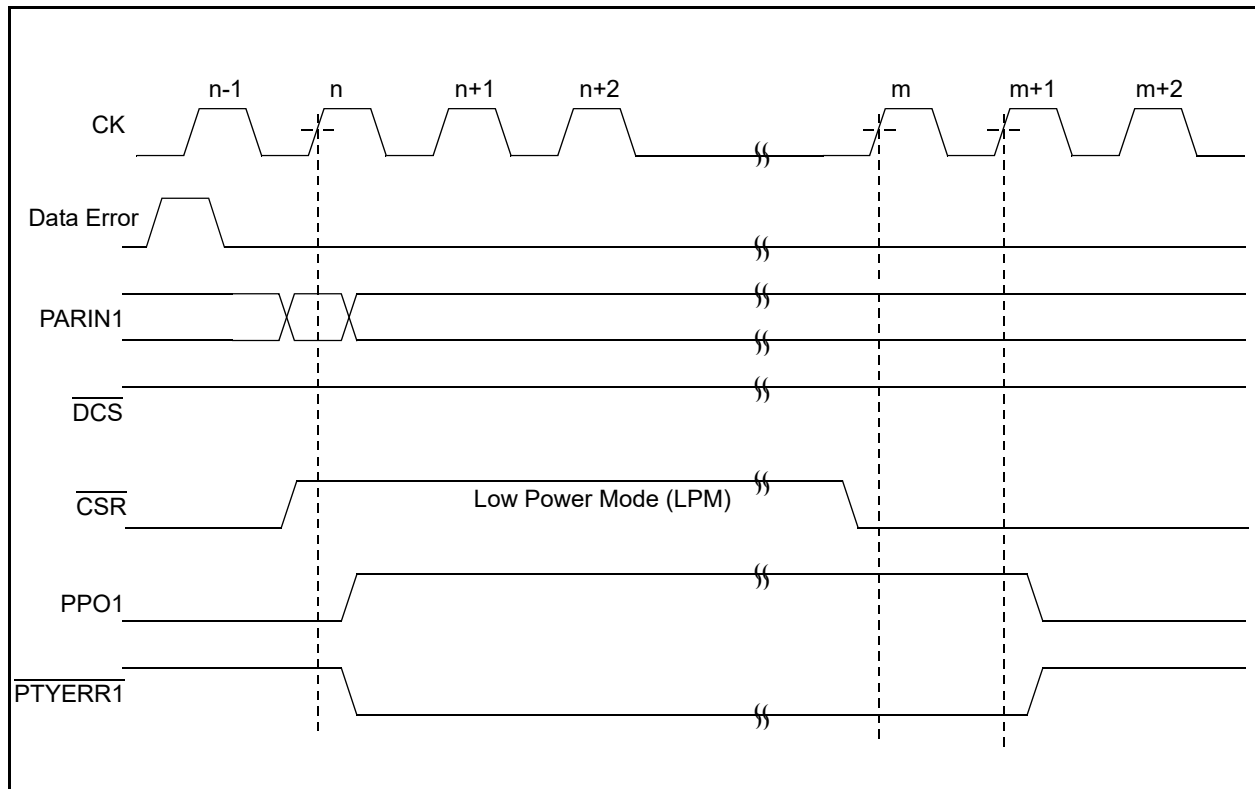


Figure 8 — 1:2A Mode, C1=0, Data Error occurs at (n-1), LPM Occurs at n

2.7 Register Timing (cont'd)

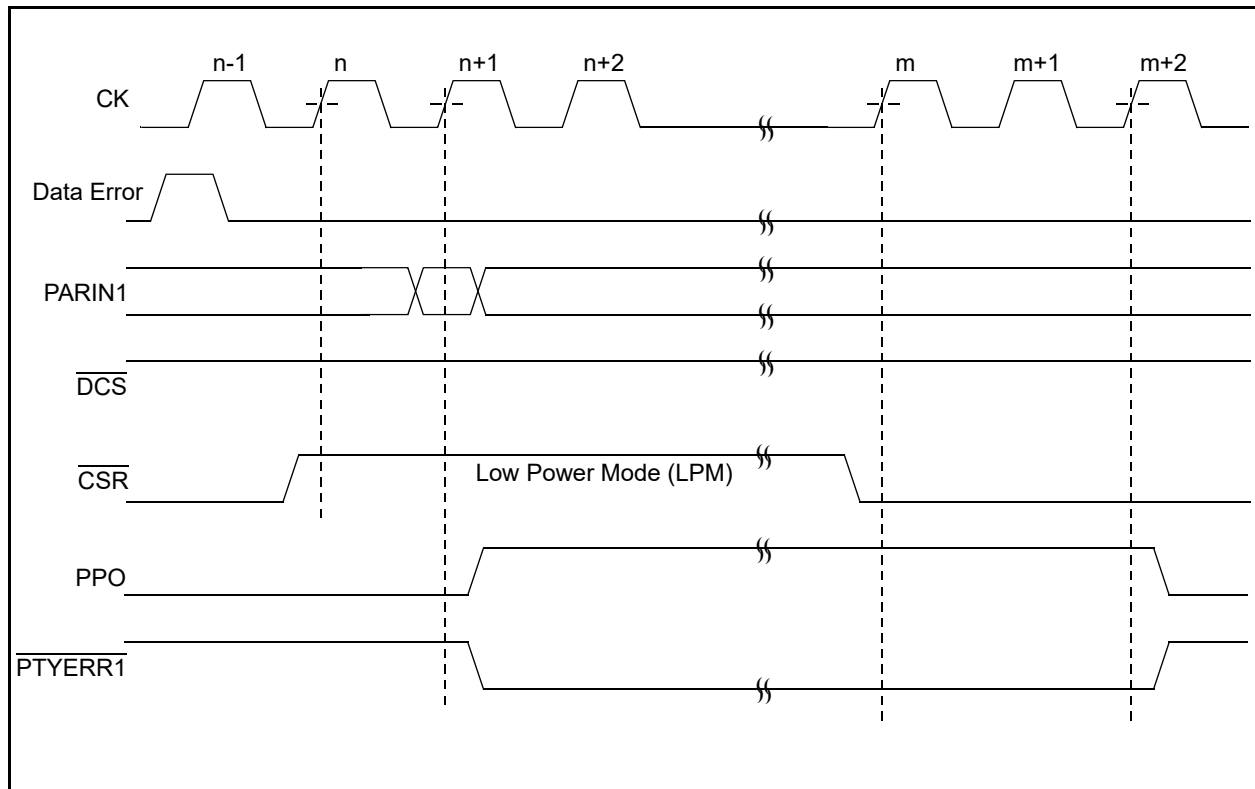
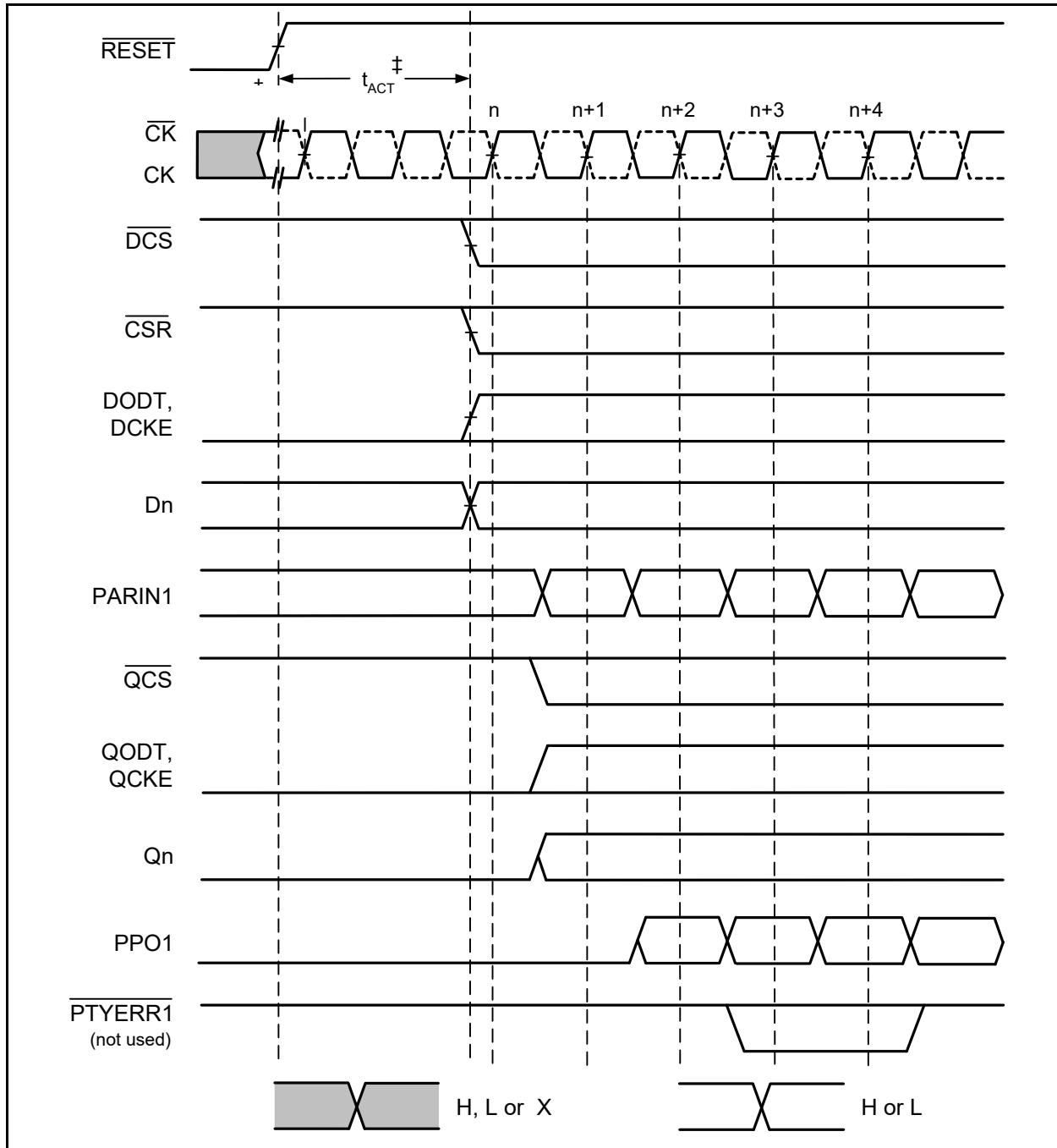


Figure 9 — 1:2B Mode, C1=1, Data Error Occurs at (n-1), LPM Occurs at n

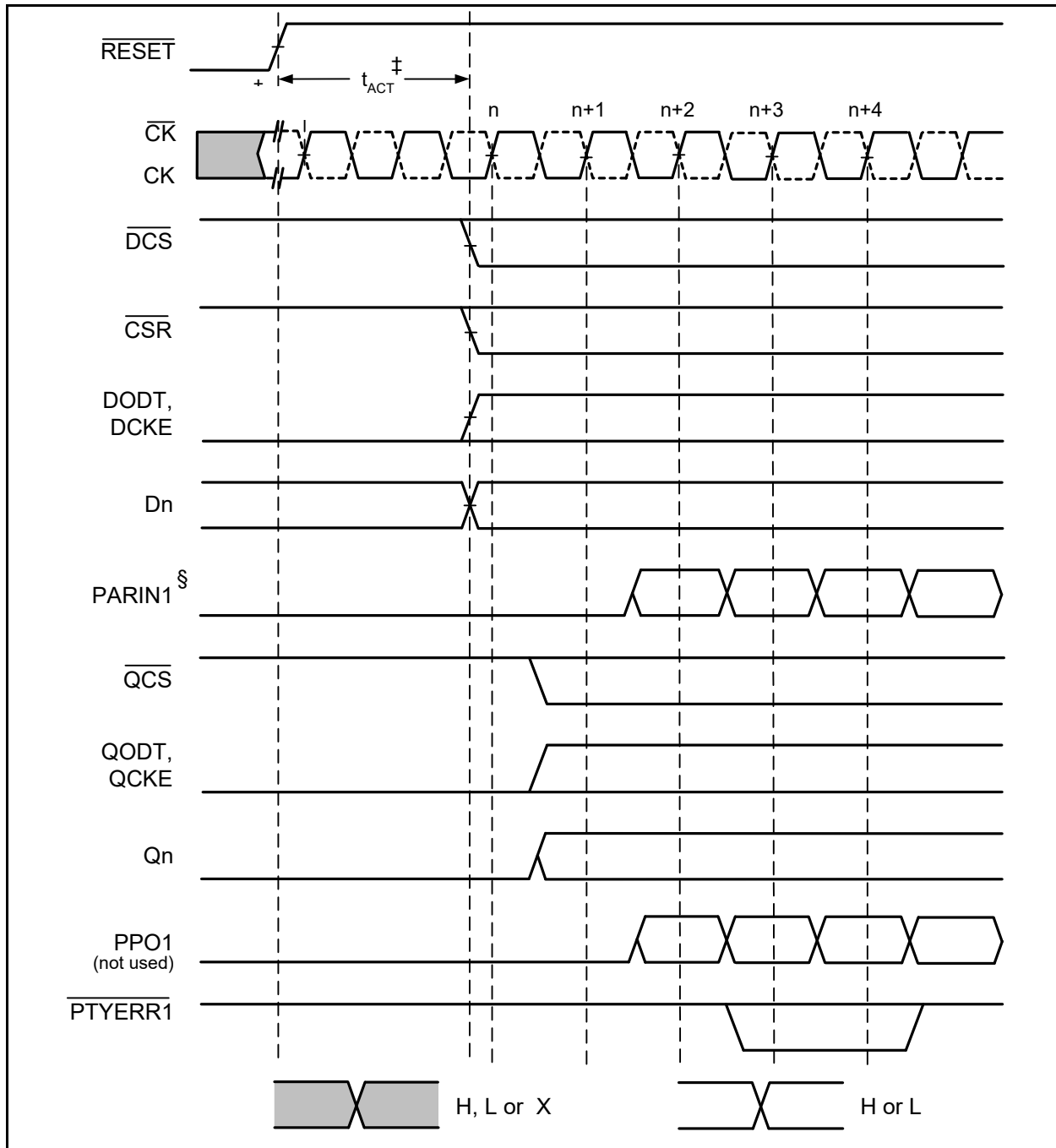
2.7 Register Timing (cont'd)



† After $\overline{\text{RESET}}$ is switched from low to high, $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ must be held HIGH, DODT0 and DCKE must be held LOW, and all other inputs must remain stable either LOW or HIGH (not floating) for a minimum time of t_{ACT} max.

Figure 10 — Timing Diagram for First Device (1:2 Register-A Configuration) Used in a Pair; C1=0; During Start-up When Data Inputs are Low or High, (RESET Switches from L to H)

2.7 Register Timing (cont'd)



† After $\overline{\text{RESET}}$ is switched from low to high, $\overline{\text{DCS}}$ and $\overline{\text{CSR}}$ must be held HIGH, DODT and DCKE must be held LOW, and all other inputs must remain stable either LOW or HIGH (not floating) for a minimum time of $t_{\text{ACT max}}$.

§ PARIN1 is driven from PPO1 of the first SSTUB32869 device

Figure 11 — Timing Diagram for Second Device (1:2 Register-B Configuration) Used in a Pair; C0=1; During Start-up When Data Inputs are Low or High, (RESET Switches from L to H)

2.8 Absolute Maximum Ratings

Table 5 — Absolute Maximum Ratings over Operating Free-air Temperature Range¹

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	Supply voltage		−0.5	+2.5	V
V_I	Receiver input voltage	See NOTES 2 and 3	−0.5	+2.5	V
V_O	Driver output voltage	See NOTES 2 and 3	−0.5	$V_{DD} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$ or $V_I > V_{DD}$	-	−50	mA
I_{OK}	Output clamp current	$V_O < 0$ or $V_O > V_{DD}$	-	±50	mA
I_O	Continuous output current	$0 < V_O < V_{DD}$	-	±50	mA
I_{CCC}	Continuous current through each V_{DD} or GND pin		-	±100	mA
T_{stg}	Storage temperature		−65	+150	°C
NOTE 1	Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.				
NOTE 2	The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.				
NOTE 3	This value is limited to 2.5 V maximum.				

Table 6 — Mode Select

C1	Device Mode
0	First Device in Pair, Front
1	Second Device in Pair, Back

2.9 Recommended Operating Conditions

Table 7 — Recommended Operating Conditions (see NOTE 1)

Symbol	Parameter	Conditions	Min	Nom	Max	Unit
V _{DD}	Supply voltage		1.7	-	1.9	V
V _{REF}	Reference voltage		$0.49 \times V_{DD}$	$0.50 \times V_{DD}$	$0.51 \times V_{DD}$	V
V _{TT}	Termination voltage		V _{REF} – 40 mV	V _{REF}	V _{REF} + 40 mV	V
V _I	Input voltage		0	-	V _{DD}	V
V _{IH}	AC HIGH-level input voltage	Data inputs	V _{REF} + 250 mV	-	-	V
V _{IL}	AC LOW-level input voltage	Data inputs	-	-	V _{REF} – 250 mV	V
V _{IH}	DC HIGH-level input voltage	Data inputs	V _{REF} + 125 mV	-	-	V
V _{IL}	DC LOW-level input voltage	Data inputs	-	-	V _{REF} – 125 mV	V
V _{IH}	HIGH-level input voltage	$\overline{\text{RESET}}$	$0.65 \times V_{DD}$	-	V _{DD}	V
V _{IL}	LOW-level input voltage	$\overline{\text{RESET}}$	-	-	$0.35 \times V_{DD}$	V
V _{ICR}	Common-mode input voltage range	CK, $\overline{\text{CK}}$	0.675	-	1.125	V
V _{ID}	Differential input voltage	CK, $\overline{\text{CK}}$	600	-	-	mV
I _{OH}	HIGH-level output current		-	-	-8	mA
I _{OL}	LOW-level output current		-	-	8	mA
I _{ERROL}	$\overline{\text{PTYERR1}}$ LOW-level output current		25			mA
T _{amb}	Operating ambient temperature in free-air		0	-	+70	°C
NOTE 1	The $\overline{\text{RESET}}$ input of the device must be held at valid levels (not floating) to ensure proper device operation. The differential inputs must not be floating, unless $\overline{\text{RESET}}$ is LOW.					

2.10 DC Specifications

Table 8 — Electrical Characteristics over Recommended Operating Free-air Temperature Range

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V_{OH}	Output HIGH voltage	$I_{OH} = -6 \text{ mA}$	1.2	-	-	V
V_{OL}	Output LOW voltage	$I_{OL} = 6 \text{ mA}$	-	-	0.5	V
I_I	Input current	All inputs, $V_I = V_{DD}$ or GND	-	-	± 5	μA
I_{DD}	Static standby current	$\overline{\text{RESET}} = \text{GND}$	-	-	200	μA
	Static operating current	$\text{RESET} = V_{DD}$; $V_I = V_{IH(AC)}$ or $V_{IL(AC)}$	-	-	80	mA
I_{DDD}	Dynamic operating current — clock only	$\overline{\text{RESET}} = V_{DD}$; $V_I = V_{IH(AC)}$ or $V_{IL(AC)}$; CK and $\overline{\text{CK}}$ switching at 50% duty cycle. $I_O = 0$; $V_{DD} = 1.9 \text{ V}$	-	†	-	$\mu\text{A}/\text{MHz}$
	Dynamic operating current — per each data input	$\overline{\text{RESET}} = V_{DD}$; $V_I = V_{IH(AC)}$ or $V_{IL(AC)}$; CK and $\overline{\text{CK}}$ switching at 50% duty cycle. One data input switching at half clock frequency, 50% duty cycle. $I_O = 0$; $V_{DD} = 1.9 \text{ V}$	-	†	-	$\mu\text{A}/\text{MHz}$
† The vendor must supply this value for full device description.						
† † The vendor must choose to comply with either single die or dual-die specification in accordance to the device implementation						

Table 9 — Capacitance Values for SSTUB32869

C_i	Input capacitance, Data inputs	$V_I = V_{REF} \pm 250 \text{ mV}$; $V_{DD} = 1.8 \text{ V}$	2.5	-	3.5	pF
	Input capacitance, Parity input	$V_I = V_{REF} \pm 250 \text{ mV}$; $V_{DD} = 1.8 \text{ V}$	2.5		3.5	pF
	Input capacitance, $\overline{\text{DCS}}n\ddagger$ / $\overline{\text{CSR}}$	$V_I = V_{REF} \pm 250 \text{ mV}$; $V_{DD} = 1.8 \text{ V}$	2.5		3.5	pF
	Input capacitance, CK and $\overline{\text{CK}}$	$V_{ICR} = 0.9 \text{ V}$; $V_{I(PP)} = 600 \text{ mV}$; $V_{DD} = 1.8 \text{ V}$	2		3	pF
	Input capacitance, $\overline{\text{RESET}}$	$V_I = V_{DD}$ or GND; $V_{DD} = 1.8 \text{ V}$	†	-	†	pF

2.11 Timing Requirements

**Table 10 — Timing Requirements over Recommended Operating Free-air Temperature Range
(see Figure 6)**

Symbol	Parameter	Conditions	Min	Max	Unit
f_{clock}	Clock frequency		-	410	MHz
t_W	Pulse duration, CK, $\overline{\text{CK}}$ HIGH or LOW		1	-	ns
t_{ACT}	Differential inputs active time	(see NOTES 1 and 2)	-	10	ns
t_{INACT}	Differential inputs inactive time	(see NOTES 1 and 3)	-	15	ns
t_{SU}	$\overline{\text{DCS}}$ to CLK, $\overline{\text{CSR}}$ high; $\overline{\text{CSR}}$ to CLK, $\overline{\text{DCS}}$ high	Chip select valid before clock switching	0.6	-	ns
	Setup time, Data, PARIN1 and $\overline{\text{DCS}}$ with $\overline{\text{CSR}}$ low	D[n], PARIN1 and $\overline{\text{DCS}}$ valid before clock switching	0.5	-	ns
t_H	Hold time	Input to remain valid after clock switching	0.4	-	ns
NOTE 1 This parameter is not necessarily production tested.					
NOTE 2 Data inputs must be active below a minimum time of t_{ACT} (max) after $\overline{\text{RESET}}$ is taken HIGH.					
NOTE 3 Data and clock inputs must be held at valid levels (not floating) a minimum time of t_{INACT} (max) after $\overline{\text{RESET}}$ is taken LOW.					

2.12 AC Specifications

Table 11 — Switching Characteristics over Recommended Operating Free-air Temperature Range (Unless Otherwise Noted) (see section 3.1)

Symbol	Parameter	Conditions	Min	Max	Unit
f_{MAX}	Maximum input clock frequency		410	-	MHz
t_{PDM}	Propagation delay	Clock to output (see NOTE 1)	1.1	1.5	ns
t_{PDMSS}	Propagation delay, simultaneous switching	Clock to output (see NOTES 1 and 2)	-	1.6	ns
t_{PD}	Propagation delay	CK and \overline{CK} to PPO1	0.5	1.6	ns
t_{LH}	Low-to-High Delay	CK and \overline{CK} to \overline{PTYERR}	1.2	3	ns
t_{HL}	High-to-Low Delay	CK and \overline{CK} to \overline{PTYERR}	1	3	ns
t_{PLH}	Low-to-High propagation delay	\overline{RESET} to \overline{PTYERR}	-	3	ns
t_{PHL}	Propagation delay	Reset to output	-	3	ns
NOTE 1 Includes 350 ps of test-load transmission line delay.					
NOTE 2 This parameter is not necessarily production tested.					

2.13 Output Buffer Characteristics

Table 12 — Output Edge Rates over Recommended Operating Free-air Temperature Range (see section 3.2)

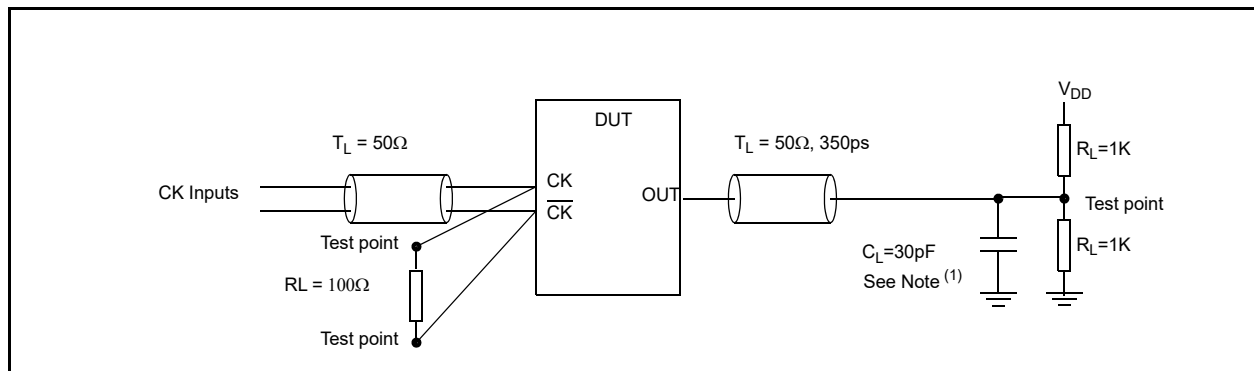
Symbol	Parameter	Conditions	Min	Max	Unit
dV/dt_r	rising edge slew rate		1	4	V/ns
dV/dt_f	falling edge slew rate		1	4	V/ns
dV/dt_{Δ}^1	absolute difference between dV/dt_r and dV/dt_f		-	1	V/ns
NOTE 1 Difference between dV/dt_r (rising edge rate) and dV/dt_f (falling edge rate).					

3 Test Circuits And Switching Waveforms

3.1 Parameter Measurement Information ($V_{DD} = 1.7V \text{ .. } 1.9V$)

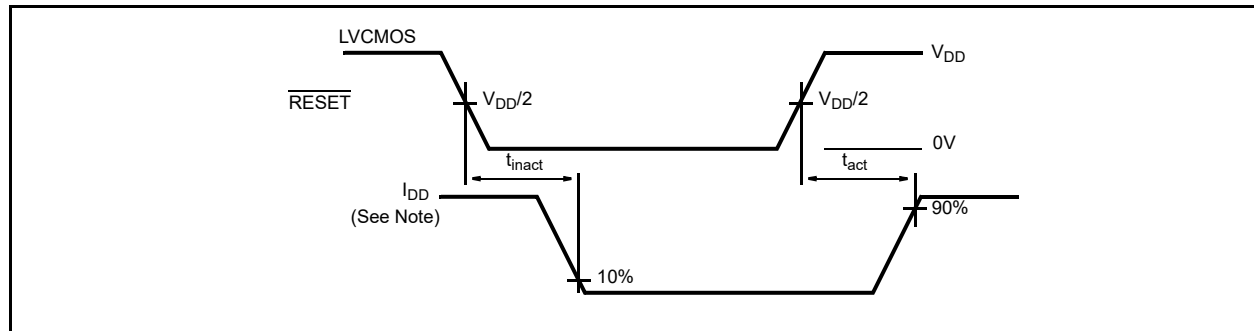
All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$; $Z_o = 50 \Omega$; input slew rate = $1 \text{ V/ns} \pm 20\%$, unless otherwise specified.

The outputs are measured one at a time with one transition per measurement.



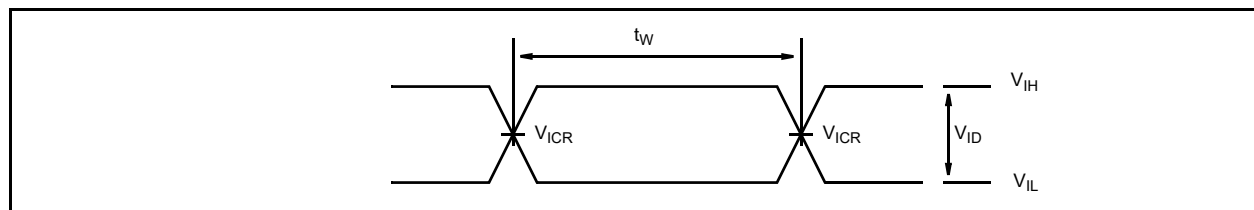
(1) C_L includes probe and jig capacitance.

Figure 12 — Load Circuit



I_{DD} tested with clock and data inputs held at V_{DD} or GND, and $I_O = 0 \text{ mA}$.

Figure 13 — Voltage and Current Waveforms; Inputs Active and Inactive Times



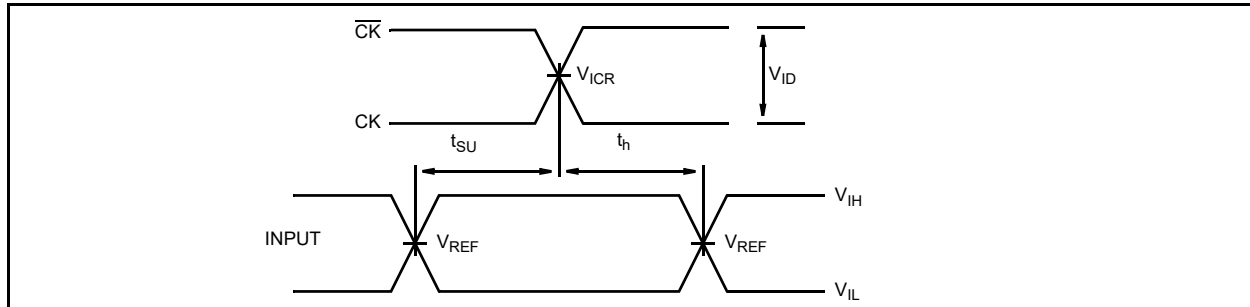
$V_{ID} = 600 \text{ mV}$

$V_{IH} = V_{REF} + 250 \text{ mV}$ (AC voltage levels) for differential inputs. $V_{IH} = V_{DD}$ for LVCMOS inputs.

$V_{IL} = V_{REF} - 250 \text{ mV}$ (AC voltage levels) for differential inputs. $V_{IL} = V_{DD}$ for LVCMOS inputs.

Figure 14 — Voltage Waveforms; Pulse Duration

3.1 Parameter Measurement Information (cont'd)



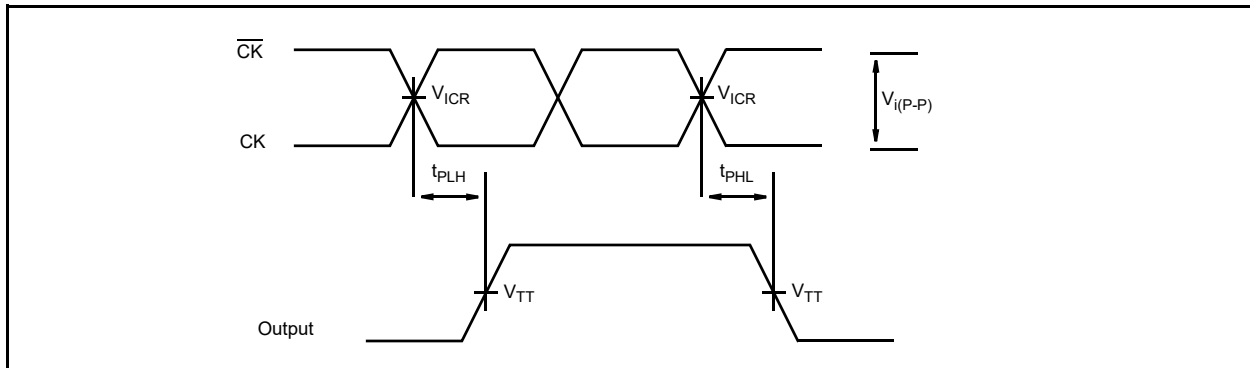
$$V_{ID} = 600 \text{ mV}$$

$$V_{REF} = V_{DD}/2$$

$$V_{IH} = V_{REF} + 250 \text{ mV (AC voltage levels) for differential inputs. } V_{IH} = V_{DD} \text{ for LVCMOS inputs.}$$

$$V_{IL} = V_{REF} - 250 \text{ mV (AC voltage levels) for differential inputs. } V_{IL} = V_{DD} \text{ for LVCMOS inputs.}$$

Figure 15 — Voltage Waveforms; Set-up and Hold Times



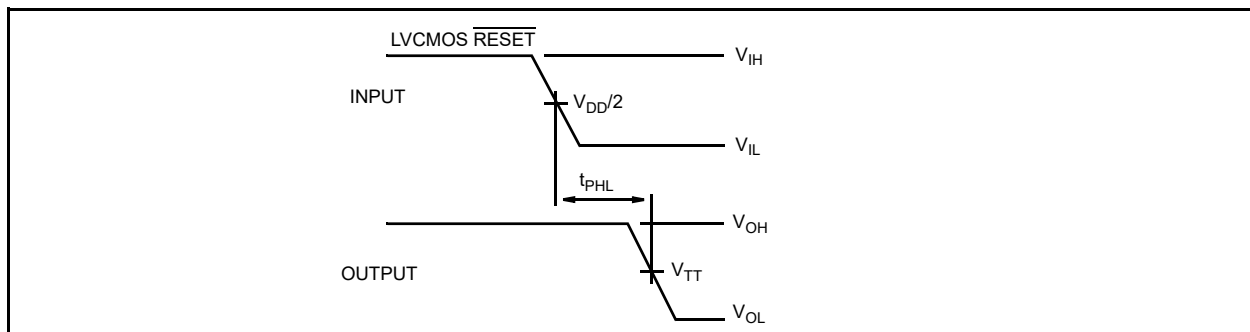
$$V_{TT} = V_{DD}/2$$

$$V_{ICR} \text{ Cross Point Voltage}$$

$$V_{i(P-P)} = 600 \text{ mV}$$

$$t_{PLH} \text{ and } t_{PHL} \text{ are the same as } t_{PD}.$$

Figure 16 — Voltage Waveforms; Propagation Delay Times



$$V_{TT} = V_{DD}/2$$

$$t_{PLH} \text{ and } t_{PHL} \text{ are the same as } t_{PD}.$$

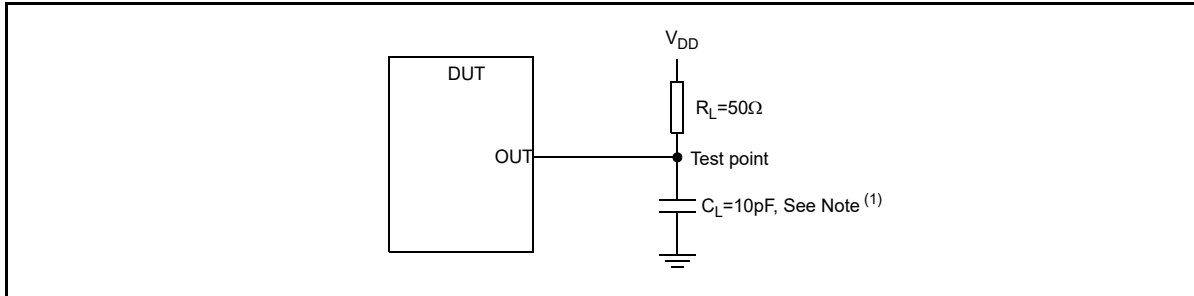
$$V_{IH} = V_{REF} + 250 \text{ mV (AC voltage levels) for differential inputs. } V_{IH} = V_{DD} \text{ for LVCMOS inputs.}$$

$$V_{IL} = V_{REF} - 250 \text{ mV (AC voltage levels) for differential inputs. } V_{IL} = V_{DD} \text{ for LVCMOS inputs.}$$

Figure 17 — Voltage Waveforms; Propagation Delay Times

3.2 Output Slew Rate Measurement Information ($V_{DD} = 1.7V \text{ .. } 1.9V$)

All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$; $Z_o = 50 \Omega$; input slew rate = $1 \text{ V/ns} \pm 20\%$, unless otherwise specified.



(1) C_L includes probe and jig capacitance.

Figure 18 — Load Circuit, HIGH-to-LOW Slew Rate Measurement

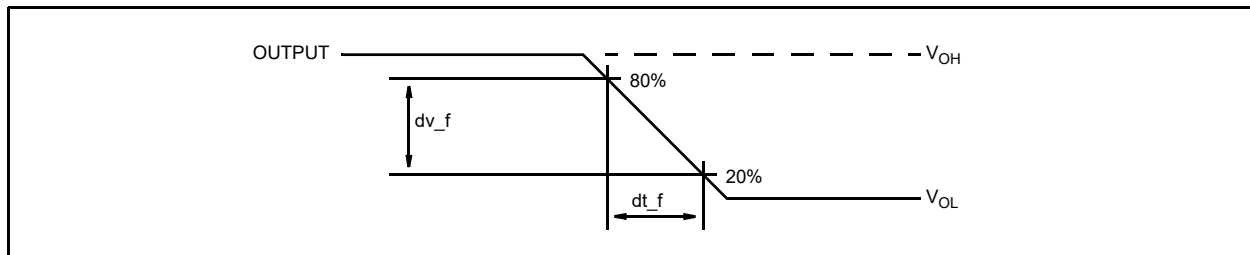
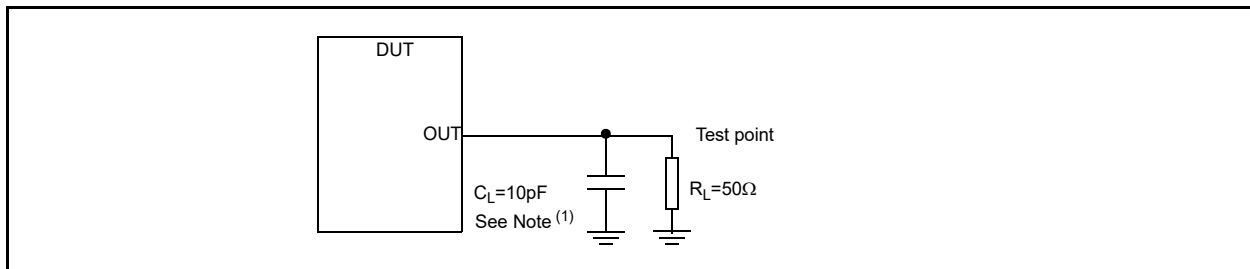


Figure 19 — Voltage Waveforms, HIGH-to-LOW Slew Rate Measurement



(1) C_L includes probe and jig capacitance.

Figure 20 — Load Circuit, LOW-to-HIGH Slew Rate Measurement

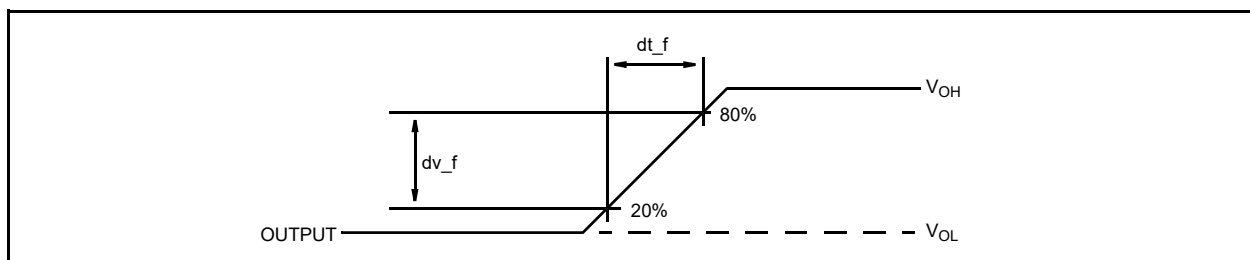
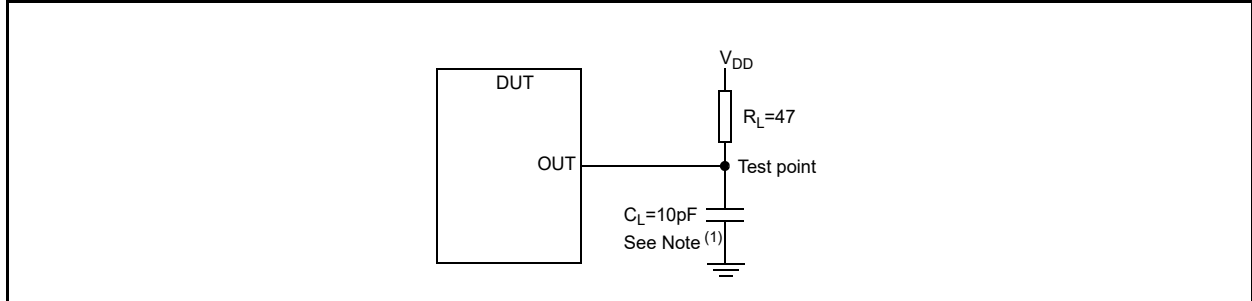


Figure 21 — Voltage Waveforms, LOW-to-HIGH Slew Rate Measurement

3.3 Error Output Load Circuit and Voltage Measurement Information ($V_{DD} = 1.7V \text{ .. } 1.9V$)

All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$; $Z_o = 50 \Omega$; input slew rate = $1 \text{ V/ns} \pm 20\%$, unless otherwise specified.



(1) C_L includes probe and jig capacitance.

Figure 22 — Load Circuit, PTYERR Outputs

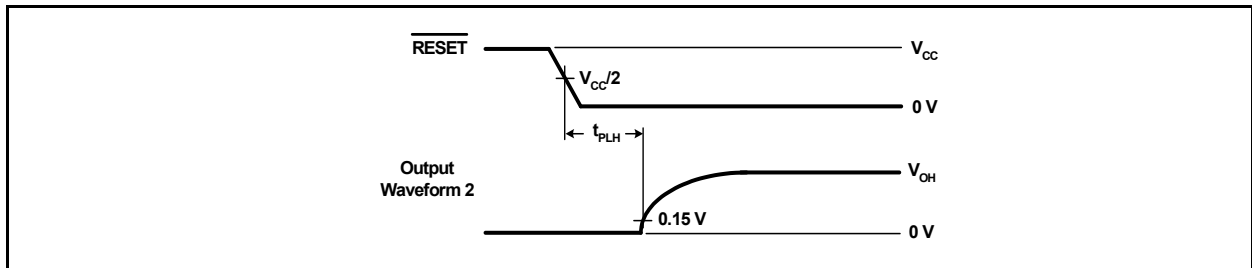
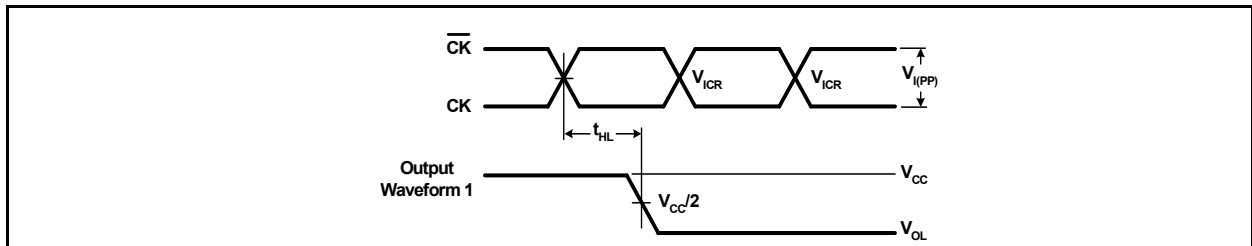


Figure 23 — Voltage Waveforms, Reset to PTYERR t_{PLH} Measurement



(1) C_L includes probe and jig capacitance.

Figure 24 — Load Circuit, CLK to PTYERR t_{PHL} Measurement

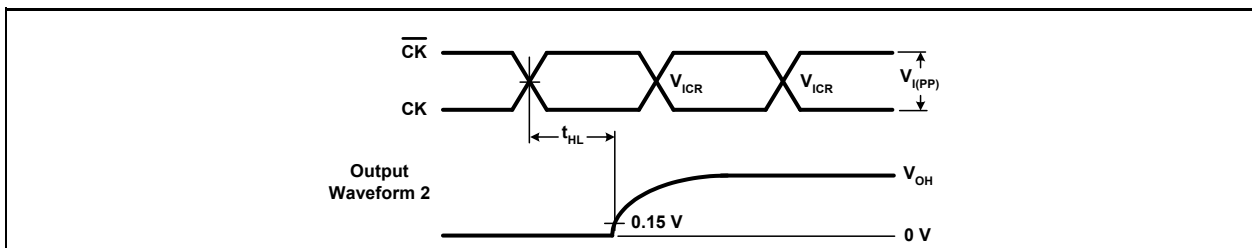
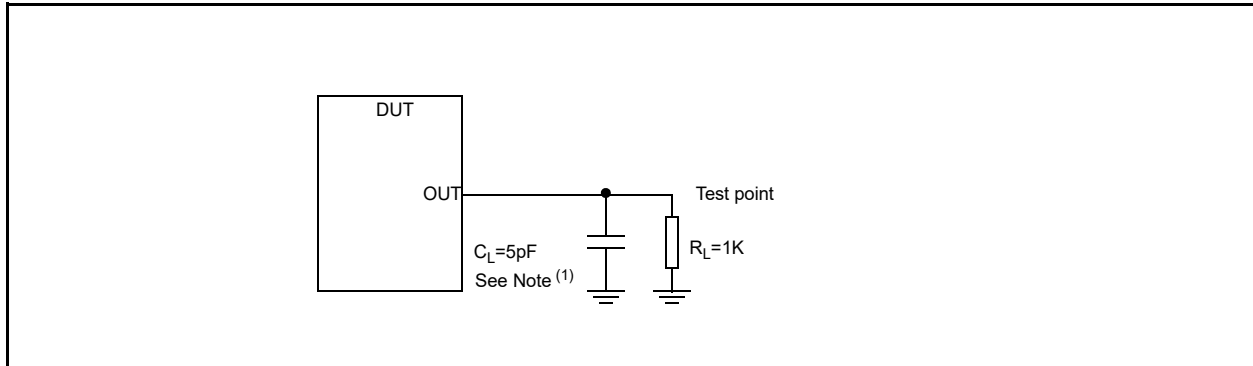


Figure 25 — Voltage Waveforms, CLK to PTYERR t_{PLH} Measurement

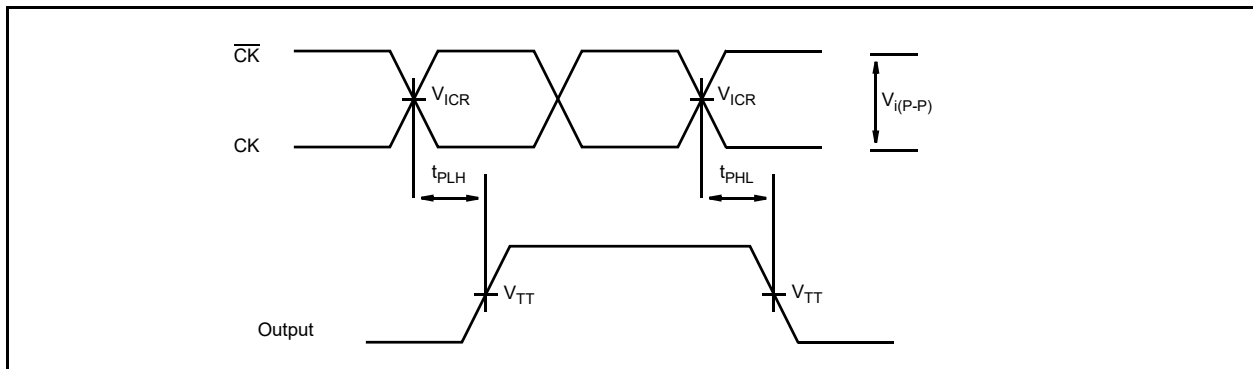
3.4 Error Output Load Circuit and Voltage Measurement Information ($V_{DD} = 1.7V \text{ .. } 1.9V$)

All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$; $Z_o = 50 \Omega$; input slew rate = $1 \text{ V/ns} \pm 20\%$, unless otherwise specified.



(1) C_L includes probe and jig capacitance.

Figure 26 — Partial Parity Out Load Circuit



$V_{TT} = V_{DD}/2$

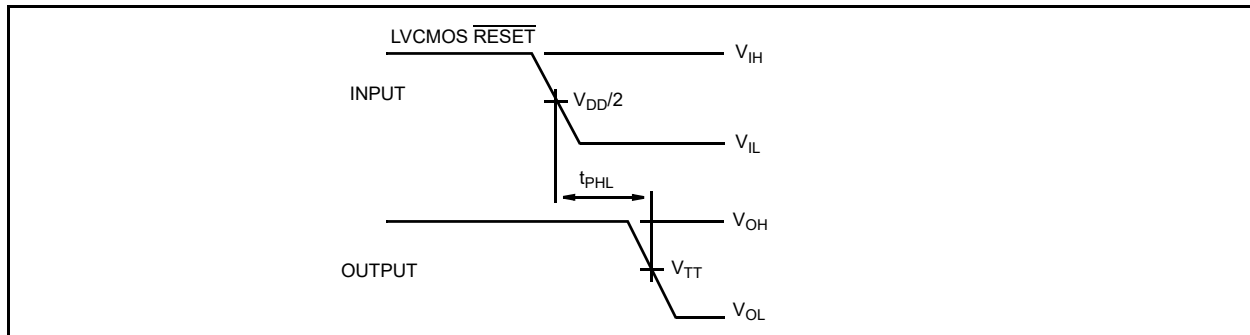
V_{ICR} Cross Point Voltage

$V_{I(P-P)} = 600 \text{ mV}$

t_{PLH} and t_{PHL} are the same as t_{PD} .

Figure 27 — Partial Parity Out Voltage Waveform, Propagation Delay Time with Respect to CLK Input

3.4 Error Output Load Circuit and Voltage Measurement Information (cont'd)



$V_{TT} = V_{DD}/2$

t_{PLH} and t_{PHL} are the same as t_{PD} .

$V_{IH} = V_{REF} + 250 \text{ mV}$ (AC voltage levels) for differential inputs. $V_{IH} = V_{DD}$ for LVC MOS inputs.

$V_{IL} = V_{REF} - 250 \text{ mV}$ (AC voltage levels) for differential inputs. $V_{IL} = V_{DD}$ for LVC MOS inputs.

Figure 28 — Voltage Waveforms; Propagation Delay Times

4 Reference to Other Applicable JEDEC Standards and Publications

- JEP95, *JEDEC Registered and Standard Outlines for Solid State and Related Products*.
- JEP104, *Reference Guide to Letter Symbols for Semiconductor Devices*.
- JESD8-7, *1.8 V +/- 0.15 V (Normal Range), and 1.2 - 1.95 V (Wide Range) Power Supply Voltage and Interface for Non-terminated Digital Integrated Circuits*.
- JESD8-15, *Stub Series Terminated Logic for 1.8 V (SSTL_18)*.
- JESD21-C, *Configuration for Solid State Memories*.
- JESD82-7, *Definition of the SSTU32864 1.8 V Configurable Registered Buffer for DDR2 RDIMM Applications*

Annex A — (Informative) Differences between JESD82-27.01 and JESD82-27

Editorial changes as follows:

1. Terminology update: Table 1 - Changed “master” to “main” for description of clock inputs CK and $\overline{\text{CK}}$
2. Updated JEDEC logos and Standard Improvement Form
3. All section headings, table titles, and figure titles changed to Initial Caps
4. Table layouts updated to JEDEC standard format
5. Removed the EIA logo from Title Page
6. Updated the NOTICE and DO NOT VIOLATE THE LAW pages
7. Added Table of Contents and List of Tables and Figures
8. Changed body text alignment from left to fully justified



Standard Improvement Form**JEDEC Standard JESD82-27.01**

The purpose of this form is to provide the Technical Committees of JEDEC with input from the industry regarding usage of the subject standard. Individuals or companies are invited to submit comments to JEDEC. All comments will be collected and dispersed to the appropriate committee(s).

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